



IC CAD Market Trends 2017

CAD Flow Investment for 2020 Production

www.garysmithEDA.com

IC CAD Market Trends 2017

CAD Flow Investment for 2020 Production

EXECUTIVE SUMMARY

It's quite a relief that electronic system level (**ESL**) growth in 2016 returned to a healthy double-digit range. The prior year brought a measly 1.5 percent growth for the ESL market, far from the level desired for an up-and-coming, next-generation set of design tools. In fact, the aberration in 2015 was primarily due to a difficult year for a single vendor (Mentor Graphics) in the ESL space, not a market-wide phenomenon. The proof that this was merely a temporary blip is borne out in looking at how 2016 growth jumped back, reassuring the industry that ESL tools aren't just a shortlived novelty. Though still not used by every design team for every project, ESL tools are certainly developing traction in the marketplace and gaining acceptance as beneficial to the design flow. We continue to anticipate robust growth for ESL in the coming years.

The register transfer level (**RTL**) tools market turned in very respectable growth in 2016. Starting with our 2014 market data, we added a new sub-application in RTL – intellectual property (IP), which significantly increases the overall size of the RTL market by about one-third. Over the past six years, the RTL-and-Below market has been continually growing, though always in the single digits. On the surface, it looks like users have continued to put steady investment into RTL and gate-level tools for the past six years, but no more than that. However, once we peel back the layers, we see that there are definitely opportunities for growth in RTL. As always, users are facing increasing time-to-market pressures but are reluctant to invest heavily in new tools and software if they can make do with the old. Designers don't have to take the time to learn new software if they are productive enough already. Meanwhile, design size and complexity are increasing, and designers need ways to handle this complexity.

The **IC CAD** market had another year of very solid growth, too. The boundaries between the traditional steps of a physical design flow – placement, CTS, routing, post-route optimization – are breaking down, and designing for routability and timing closure becomes necessary as early as the power grid creation stage. This calls for different design flows than what exists today. Power integrity optimization needs to be taken in as a proactive step at the floorplanning/power grid stage instead of a reactive step later in the backend process. Shifting to 10nm and 7nm (for 2020 production) means a need to work closely together in multidiscipline approaches and crossing the boundaries of traditional design flow steps, in order to allow for design convergence and timing closure. It also means that over-the-wall delivery (e.g. from a team in the US to another in India, for instance) is very challenging and will put stress on some of the existing organization structures built around the traditional flow.

In 2016, positive growth returned for printed circuit board (**PCB**) tools. The challenges facing many PCB engineers are to develop high precision CAM tooling, advanced data integrity tools and next generation power tools. PCB engineers have found total allotted design cycle time decreased, especially as incredibly

complex chip processes, new materials, advanced package designs and board level connectivity advanced from research to reality. Design flow errors, waste and product recalls, re-work and extra prototypes increased and costs exceeded original budgets. Adding layers of complexity requires different layers of integration and increases power supplies and power consumption. The “next generation” of products requires new solutions that reduce wiring, coding, time to market, cost and improve efficiency.

Slicing and Dicing Market Statistics Data

Like so many technology industries, EDA is perpetually facing new technical and business challenges. Between progressing to an era of System Level Design and contending with the world of Internet of Things (IoT) designs, we need to look at the market, and therefore the numbers, from other perspectives. Design methodologies and business requirements are often developed within vertical industry markets. There is no single, overarching systems market for all types of end products; fighter jets and cell phone have vastly different design challenges, after all. Therefore, it makes sense to present Market Trends data in an alternate way also, to correspond to this vertical industry approach.

These types of second-cut data reports are usually created on an on-demand basis. With frequent demand, though, a second-cut report may become standard report. As the system level design methodology begins to take shape, we may extend our reporting into multiple industry reports, depending on demand.

INTRODUCTION

The IC CAD market includes tools used to implement layout designs into silicon. Traditional CAD models focused on long design cycles from multiple and costly design rework cycles. For quite some time, as a result of mergers, collaborations and acquisitions, EDA vendors, semiconductor and systems companies have teamed to develop multiple platforms and system design flows. IC CAD market vendor revenue reached \$2,195.2 million in 2016. The IC CAD market covered in this report is segmented into four main categories: IC Place and Route, Physical Verification, Physical Libraries and Tools, and IC CAM. There are more than 12 sub-applications within these four categories that contain market share updates.

OVERVIEW

This report comprises the IC CAD section of the EDA Market Trends. The IC CAD market covered in this report is segmented into four main categories: IC Place and Route, Physical Verification, Physical Libraries and Tools, and IC CAM. In this report we will discuss market share, trends, and forecasts for the IC CAD sub-applications that are most significant in the overall EDA landscape. Readers should note that we classify design tools at their highest level of use.

CLICK HERE TO PURCHASE

**IC CAD Market Trends 2017:
CAD Flow Investment for 2020 Production**



IC CAD Market Trends 2017
CAD Flow Investment for 2020 Production



TABLE OF CONTENTS

Page	Title
1	Market Trends 2017 Leading the Pack to 7nm Designs
2	IC Place and Route
3	ASIC Layout
4	Custom Layout Physical Verification
5	Design Rule Checkers (DRC)
6	Extraction
7	Physical Analysis Tools
8	IC SPICE
9	Physical Libraries and Tools
10	IC CAM

TABLE OF FIGURES

Page	Title
1	Figure C-1: Top Five IC CAD Vendors 2016
3	Figure C-2: ASIC Layout Market Share 2016
	Figure C-3: ASIC Layout Forecast
4	Figure C-4: Custom Layout Market Share 2016
	Figure C-5: Custom Layout Forecast
6	Figure C-6: DRC Market Share 2016
	Figure C-7: Extraction Market Share 2016
7	Figure C-8: Physical Verification (DRC and Extraction) Forecast
	Figure C-9: Physical Analysis Tools Market Share 2016
8	Figure C-10: Physical Analysis Forecast
9	Figure C-11: IC SPICE Market Share 2016
	Figure C-12: IC SPICE Market Forecast
10	Figure C-13: Physical Libraries Market Share 2016
	Figure C-14: Physical Libraries Forecast
11	Figure C-15: IC CAM Market Share 2016
	Figure C-16: IC CAM Forecast
12	Appendix A: IC CAD Market Trends Forecast

CLICK HERE TO PURCHASE

**IC CAD Market Trends 2017:
CAD Flow Investment for 2020 Production**

\$2,000